



Standard Practice for Preparation of Tungsten and Tungsten Alloys for Electroplating¹

This standard is issued under the fixed designation B 482; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ϵ) indicates an editorial change since the last revision or reapproval.

INTRODUCTION

Because of the high melting point of tungsten, (3410°C) this metal and its alloys are used in ultra-high-temperature applications. However, tungsten oxidizes readily and the oxides offer little or no protection to the metal because they melt or sublime below 2200°C. Tungsten has a body-centered-cubic structure as does chromium. Its coefficient of thermal expansion is $4.3 \mu\text{m/m} \cdot ^\circ\text{C}$; the coefficient of chromium is $6.1 \mu\text{m/m} \cdot ^\circ\text{C}$, therefore, chromium-coated tungsten offers a reasonable match based on crystal structure and coefficient of thermal expansion. The effect of hydrogen must be considered in the design of coating systems for tungsten. Molecular hydrogen when trapped under a coating can result in failure of the part. Although failure can occur if the adhesion of the coating to the tungsten is inadequate, failure within the basis metal as rupture at laminations of stringers has been observed with off-grade tungsten.

1. Scope

1.1 This practice makes recommendations of several reported practices for electroplating on tungsten and its alloys along with comments as a guide in the selection of a processing method for a given application. Because data on methods and results of evaluation with electroplated coatings on tungsten are limited, a recommendation of one method over another cannot be made.

1.2 *This standard does not purport to address the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.*

2. Processes

2.1 The several processes reported for electroplating on tungsten can be classified as either (1) providing as-deposited adhesion of the coatings or (2) depending on diffusion alloy bonding to provide such adhesion. Appraisal of the relative merits of these processes depends on the application for the coating.

2.2 Precleaning:

2.2.1 The need for descaling, solvent cleaning, and alkaline-soak cleaning of tungsten is dictated by the degree of cleanliness of the surface to be coated. Remove gross scale and surface imperfections by mechanical means. Remove grease and oil by organic solvents. Remove saponifiable and dispersible surface dirt by soak cleaning in a hot alkaline cleaner.

2.2.2 Anodic treatment of tungsten surfaces in a 5 to 25 mass % sodium hydroxide solution at $71 \pm 6^\circ\text{C}$ and 16 to 25 A/dm^2 can be used to remove undesired surface metal. Anodic etching in a 10 mass % hydrofluoric acid electrolyte at $24 \pm 3^\circ\text{C}$ and $5.4 \text{A}/\text{dm}^2$ can be used to remove light scale and undesired surface metal before activation and electroplating of tungsten.

2.3 *Activation and Electroplating*—Two alternative methods are presented below. The selection of one process over the other should be based on preliminary experimentation. Both procedures produce as-deposited adhesion of electroplated metals on tungsten.

2.3.1 *Methods 1²*—Treat the precleaned tungsten in a hydrofluoric acid electrolyte (30 ± 10 mass % HF) at $24 \pm 3^\circ\text{C}$, using 2 to 5 V, 60-Hz ac, and 2 to 5 A/dm^2 for 1 to 2 min. Either divide the work between two work rods or make one electrode of platinum. After rinsing, the work is electroplated in acid electrolytes.

¹ This practice is under the jurisdiction of ASTM Committee B08 on Metallic and Inorganic Coatings and is the direct responsibility of Subcommittee B08.02 on Pre Treatment.

Current edition approved Feb. 10, 2003. Published May 2003. Originally approved in 1968. Last previous edition approved in 1998 as B 482 – 85 (1998).

² Cannizaro, J. J., U.S. Patent No. 2,433,651, June, 1948.

2.3.2 *Method 2*—Electroplate the precleaned tungsten with a chromium strike prior to subsequent electroplating with other metals^{3,4} using the following processing steps:

2.3.2.1 *Anodic Etch*—Etch anodically at 10 to 30 A/dm² in the following solution for 2 to 5 min.

KOH	30 mass %
Temperature	48 to 60°C

2.3.2.2 *Rinse*.

2.3.2.3 *Acid Neutralize*—Immerse for 1 min in 10 mass % sulfuric acid at 27 ± 6°C.

2.3.2.4 *Rinse*.

2.3.2.5 *Chromium Strike*—Strike at 15 to 25 A/dm² in the following chromium solution for 1 to 3 min. Enter the solution with the parts cathodic.

CrO ₃	250 g/L
H ₂ SO ₄	2.5 g/L
Temperature	60 to 72°C

2.3.2.6 *Rinse*.

2.3.2.7 *Acid Activation*—Immerse in 20 mass % hydrochloric acid at 21 to 33°C for 2 to 5 s.

2.3.2.8 *Nickel Strike*—Strike at 5 to 10 A/dm² in the following nickel solution for 2 to 5 min.

NiSO ₄ · 6H ₂ O	240 g/L
H ₂ SO ₄	40 g/L
Temperature	21 to 33°C

2.3.2.9 *Rinse*.

2.3.2.10 *Electroplate*—Electroplate with desired metal.

2.4 *Alloying and Heating Effects*:

2.4.1 A number of other processes, involving heat treating (927 ± 56°C) to diffusion-alloy bond an electrodeposited coating to the basis tungsten have been proposed but offer no apparent advantage.

2.4.2 Chromium-strike coated tungsten^{3,4} subsequently electroplated with nickel and heated for ½ h at 980°C shows no deterioration of the electroplated coatings. Chromium-tungsten diffusion does not form the weak brittle intermetallic alloy zones such as are evident when nickel, iron, or cobalt coatings on tungsten are similarly heat treated.

³ Korbek, A., U.S. Patent No. 2,697,130, Dec. 14, 1954.

⁴ Marzano, C., "Plating on Tungsten," *Plating*, Vol 51, 1964, pp. 207–211.

ASTM International takes no position respecting the validity of any patent rights asserted in connection with any item mentioned in this standard. Users of this standard are expressly advised that determination of the validity of any such patent rights, and the risk of infringement of such rights, are entirely their own responsibility.

This standard is subject to revision at any time by the responsible technical committee and must be reviewed every five years and if not revised, either reapproved or withdrawn. Your comments are invited either for revision of this standard or for additional standards and should be addressed to ASTM International Headquarters. Your comments will receive careful consideration at a meeting of the responsible technical committee, which you may attend. If you feel that your comments have not received a fair hearing you should make your views known to the ASTM Committee on Standards, at the address shown below.

This standard is copyrighted by ASTM International, 100 Barr Harbor Drive, PO Box C700, West Conshohocken, PA 19428-2959, United States. Individual reprints (single or multiple copies) of this standard may be obtained by contacting ASTM at the above address or at 610-832-9585 (phone), 610-832-9555 (fax), or service@astm.org (e-mail); or through the ASTM website (www.astm.org).